

H48-6C

Thermal Conductive Pad



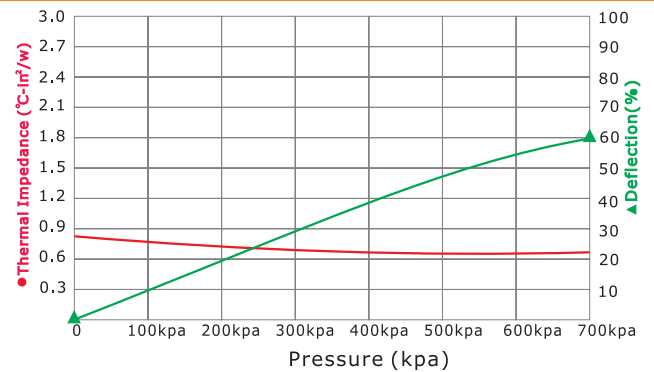
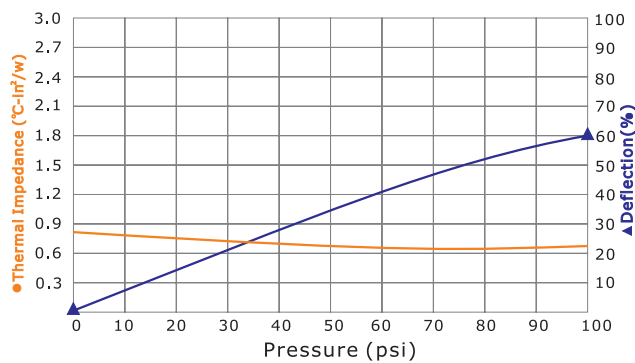
Features

Very good thermal conductivity
Very soft and compressible
Natural tack
Easy to assemble
Very good insulator

Applications

Electronic components: IC / CPU / MOS
LED / M/B / P/S / Heat Sink / LCD-TV / Notebook PC / PC / Telecom Device /
Wireless Hub etc....
DDR II Module / DVD Applications / Hand-Set applications etc...

Thermal Resistance V.S Pressure V.S Deflection

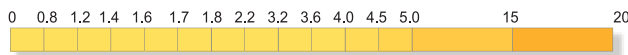


Properties

REACH Compliant

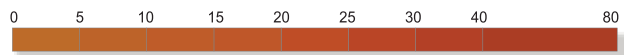
RoSH Compliant

Thermal Conductivity: 3.2 W/mK
(W/mK - Z Axis)



Testing sample thickness : 1.0 mm

Hardness: 15 (Shore A)
(Shore A)



In the thermal resistance vs pressure vs deflection charts H48-6C provides low thermal impedance.
As the pressure increases the thermal impedance decreases. H48-6C provides good compliance and softness.

Property	H48-6C	Unit	Tolerance	Test Method
Colour	Dark grey	-	-	Visual
Thickness (Available thickness range)	0.3 - 20	mm	-	ASTM D374
	0.0118 - 0.787	inch	-	ASTM D374
Thermal Conductivity	3.2	W/mK	-	ASTM D5470
Flammability Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	>5	kV/mm	-	ASTM D149
Weight Loss	<1	%	-	ASTM E595
Specific Gravity	2.42	g/cm ³	±0.2	ASTM D792
Working Temperature	-40 to 200	°C	-	-
Volume Resistance	>10 ¹¹	Ohm-cm	-	ASTM D257
Elongation	130	%	±13	ASTM D412
Tensile Strength	8	Kgf/cm ²	±2	ASTM D412
Standard Shape	-	Sheets 320-320mm	-	-
Hardness	15	Shore A	±5	ASTM D2240

Available with an adhesive backing

